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BFG540; BFG540/X; BFG540/XR

NPN 9 GHz wideband transistor

Rev. 05 — 21 November 2007

Product data sheet

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NXP Semiconductors

NPN 9 GHz wideband transistor

BFG540; BFG540/X; BFG540/XR

FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

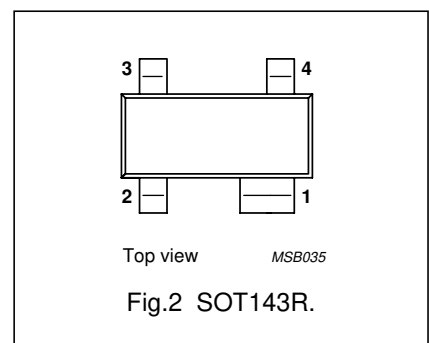
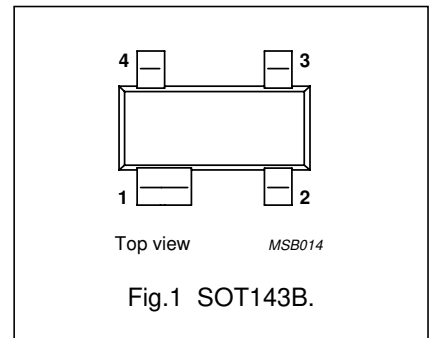
DESCRIPTION

NPN silicon planar epitaxial transistors, intended for wideband applications in the GHz range, such as analog and digital cellular telephones, cordless telephones (CT1, CT2, DECT, etc.), radar detectors, satellite TV tuners (SATV), MATV/CATV amplifiers and repeater amplifiers in fibre-optical systems.

The transistors are mounted in plastic SOT143B and SOT143R packages.

PINNING

PIN	DESCRIPTION
BFG540 (Fig.1) Code: %MG	
1	collector
2	base
3	emitter
4	emitter
BFG540/X (Fig.1) Code: %MM	
1	collector
2	emitter
3	base
4	emitter
BFG540/XR (Fig.2) Code: %MR	
1	collector
2	emitter
3	base
4	emitter



NPN 9 GHz wideband transistor

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BFG540/XR

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	20	V
V_{CES}	collector-emitter voltage	$R_{BE} = 0$	–	–	15	V
I_C	DC collector current		–	–	120	mA
P_{tot}	total power dissipation	$T_s \leq 60\text{ °C}$; note 1	–	–	400	mW
h_{FE}	DC current gain	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $T_j = 25\text{ °C}$	100	120	250	
C_{re}	feedback capacitance	$I_C = 0$; $V_{CE} = 8\text{ V}$; $f = 1\text{ MHz}$	–	0.5	–	pF
f_T	transition frequency	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 1\text{ GHz}$; $T_{amb} = 25\text{ °C}$	–	9	–	GHz
G_{UM}	maximum unilateral power gain	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	–	18	–	dB
		$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 2\text{ GHz}$; $T_{amb} = 25\text{ °C}$	–	11	–	dB
$ S_{21} ^2$	insertion power gain	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	15	16	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}$; $I_C = 10\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	–	1.3	1.8	dB
		$\Gamma_s = \Gamma_{opt}$; $I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	–	1.9	2.4	dB
		$\Gamma_s = \Gamma_{opt}$; $I_C = 10\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 2\text{ GHz}$; $T_{amb} = 25\text{ °C}$	–	2.1	–	dB

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	20	V
V_{CES}	collector-emitter voltage	$R_{BE} = 0$	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	2.5	V
I_C	DC collector current		–	120	mA
P_{tot}	total power dissipation	$T_s \leq 60\text{ °C}$; note 1	–	400	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C

Note

- T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point	$T_s \leq 60\text{ °C}$; note 1	290	K/W

Note

- T_s is the temperature at the soldering point of the collector pin.

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BFG540; BFG540/X;
BFG540/XR

CHARACTERISTICS

 $T_j = 25\text{ °C}$ unless otherwise specified.

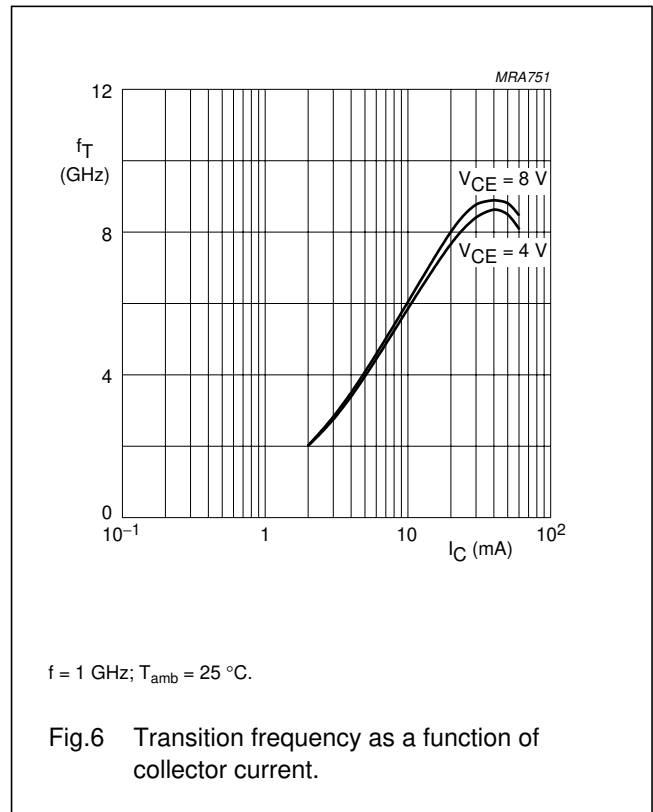
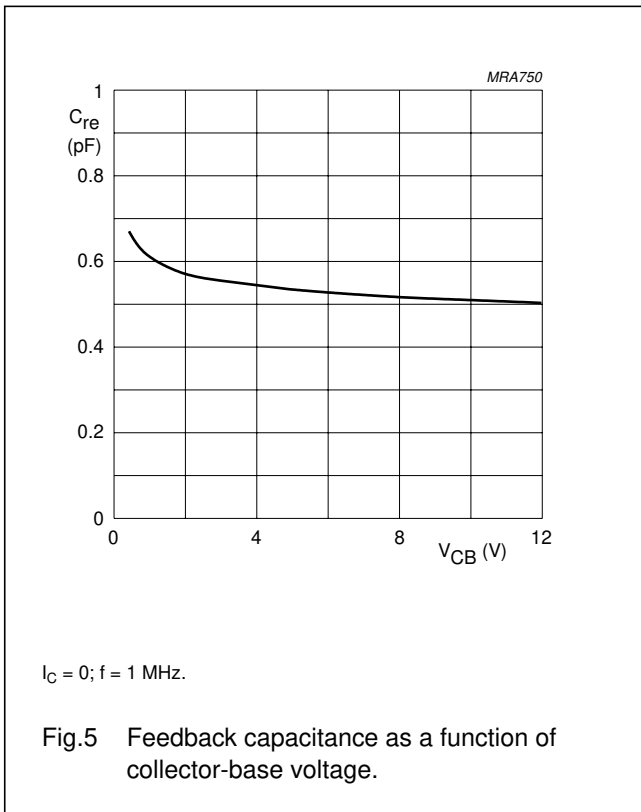
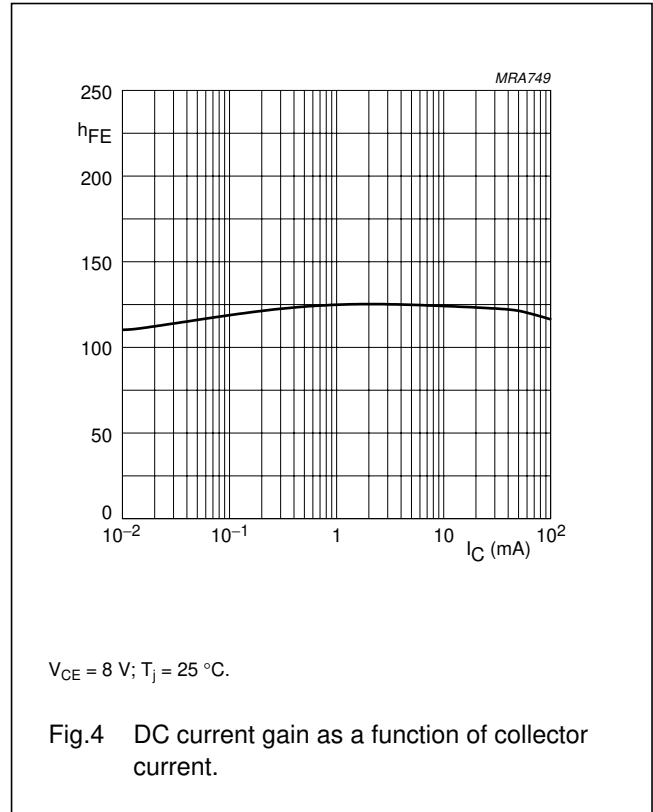
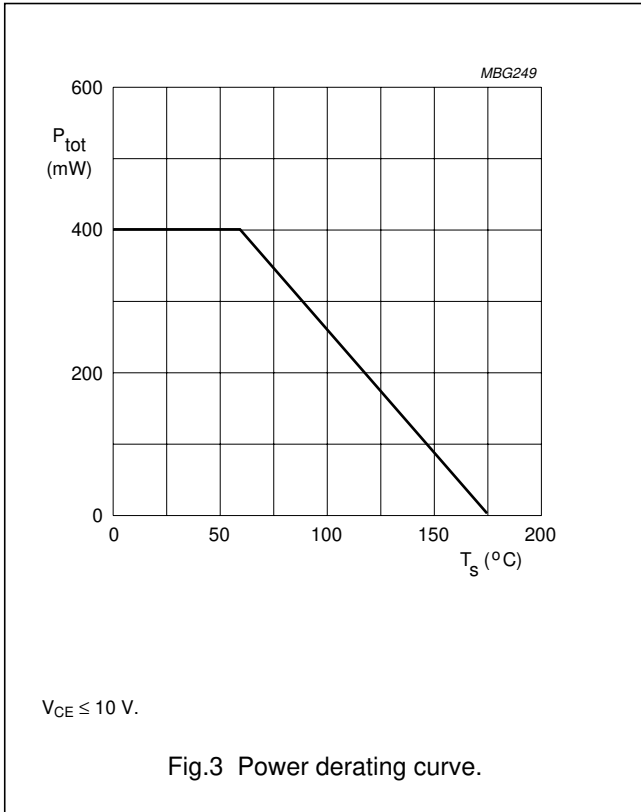
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0$; $V_{CB} = 8\text{ V}$	–	–	50	nA
h_{FE}	DC current gain	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$	60	120	250	
C_e	emitter capacitance	$I_C = I_C = 0$; $V_{EB} = 0.5\text{ V}$; $f = 1\text{ MHz}$	–	2	–	pF
C_c	collector capacitance	$I_E = I_E = 0$; $V_{CB} = 8\text{ V}$; $f = 1\text{ MHz}$	–	0.9	–	pF
C_{re}	feedback capacitance	$I_C = 0$; $V_{CB} = 8\text{ V}$; $f = 1\text{ MHz}$	–	0.5	–	pF
f_T	transition frequency	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 1\text{ GHz}$; $T_{amb} = 25\text{ °C}$	–	9	–	GHz
G_{UM}	maximum unilateral power gain (note 1)	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	–	18	–	dB
		$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 2\text{ GHz}$; $T_{amb} = 25\text{ °C}$	–	11	–	dB
$ S_{21} ^2$	insertion power gain	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	15	16	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}$; $I_C = 10\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	–	1.3	1.8	dB
		$\Gamma_s = \Gamma_{opt}$; $I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	–	1.9	2.4	dB
		$\Gamma_s = \Gamma_{opt}$; $I_C = 10\text{ mA}$; $V_{CE} = 8\text{ V}$; $f = 2\text{ GHz}$; $T_{amb} = 25\text{ °C}$	–	2.1	–	dB
P_{L1}	output power at 1 dB gain compression	$I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $R_L = 50\text{ }\Omega$; $f = 900\text{ MHz}$; $T_{amb} = 25\text{ °C}$	–	21	–	dBm
ITO	third order intercept point	note 2	–	34	–	dBm
V_O	output voltage	note 3	–	500	–	mV
d_2	second order intermodulation distortion	note 4	–	–50	–	dB

Notes

- G_{UM} is the maximum unilateral power gain, assuming s_{12} is zero and $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1 - |s_{11}|^2)(1 - |s_{22}|^2)}$ dB.
- $V_{CE} = 8\text{ V}$; $I_C = 40\text{ mA}$; $R_L = 50\text{ }\Omega$; $T_{amb} = 25\text{ °C}$;
 $f_p = 900\text{ MHz}$; $f_q = 902\text{ MHz}$;
measured at $f_{(2p-q)} = 898\text{ MHz}$ and $f_{(2q-p)} = 904\text{ MHz}$.
- $d_{im} = -60\text{ dB}$ (DIN 45004B); $I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $Z_L = Z_S = 75\text{ }\Omega$; $T_{amb} = 25\text{ °C}$;
 $V_p = V_O$; $V_q = V_O - 6\text{ dB}$; $V_r = V_O - 6\text{ dB}$;
 $f_p = 795.25\text{ MHz}$; $f_q = 803.25\text{ MHz}$; $f_r = 805.25\text{ MHz}$;
measured at $f_{(p+q-r)} = 793.25\text{ MHz}$.
- $I_C = 40\text{ mA}$; $V_{CE} = 8\text{ V}$; $V_O = 275\text{ mV}$; $T_{amb} = 25\text{ °C}$;
 $f_p = 250\text{ MHz}$; $f_q = 560\text{ MHz}$; measured at $f_{(p+q)} = 810\text{ MHz}$.

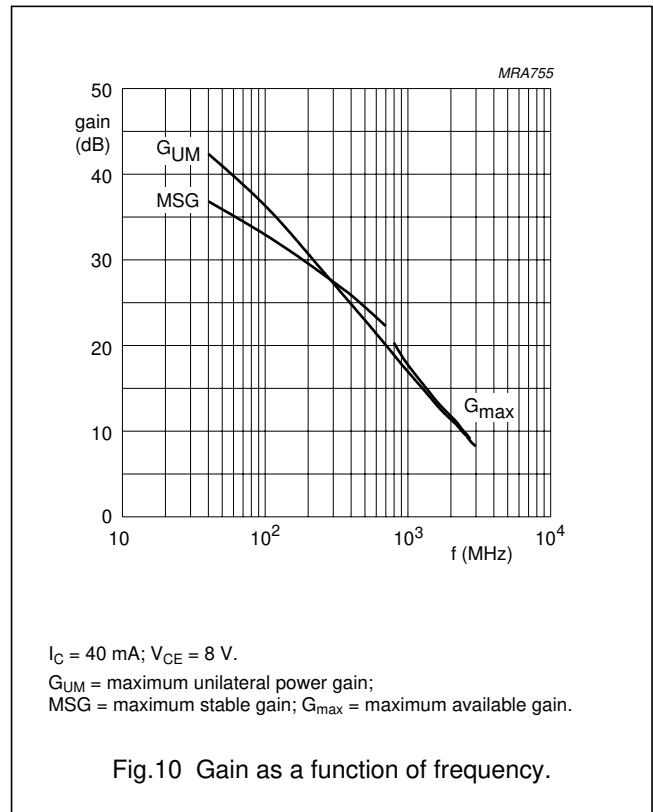
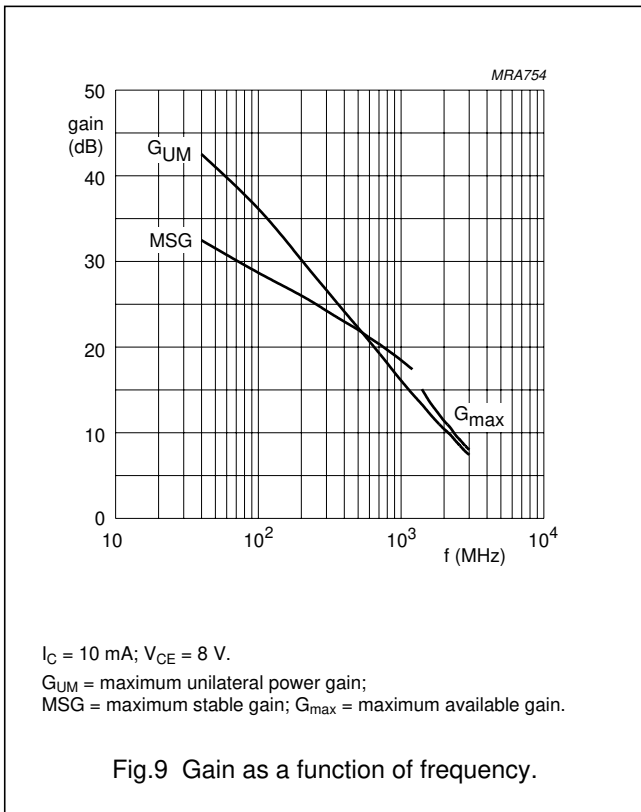
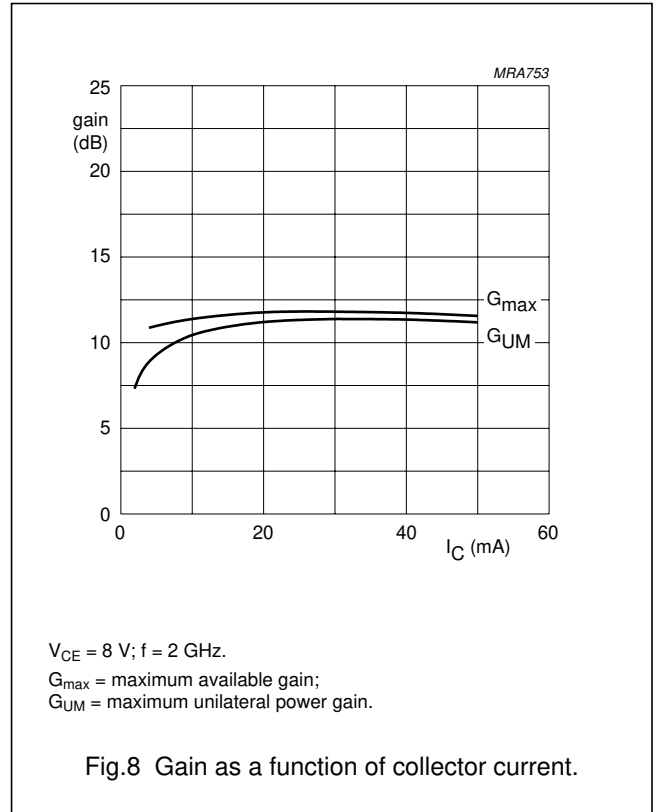
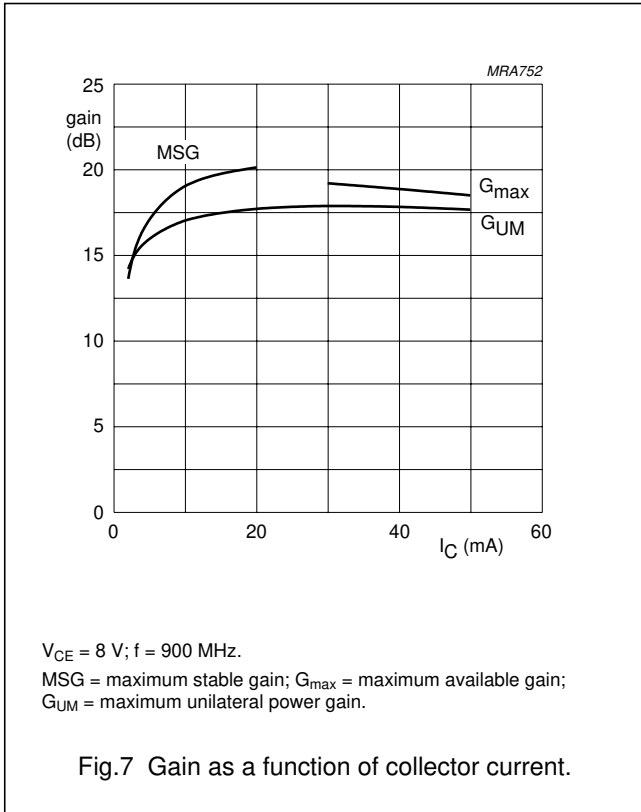
NPN 9 GHz wideband transistor

BFG540; BFG540/X;
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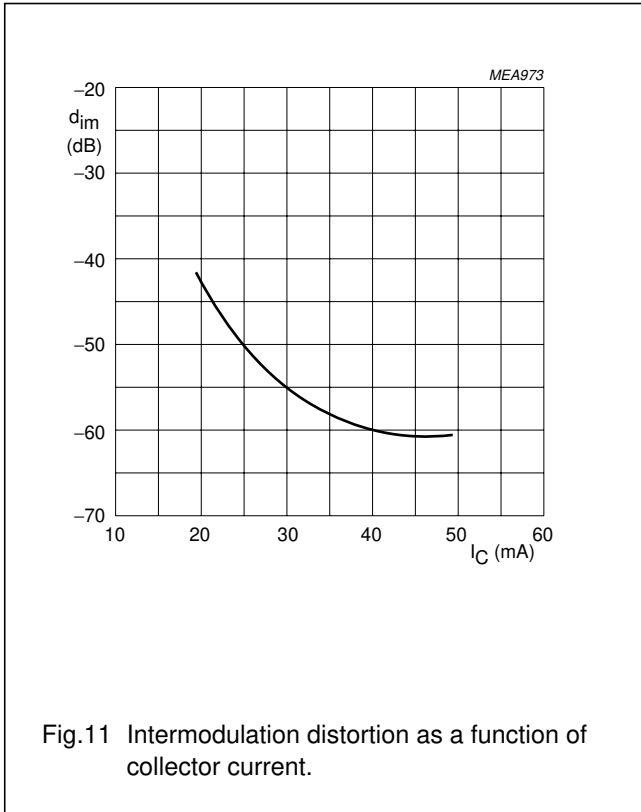


Fig.11 Intermodulation distortion as a function of collector current.

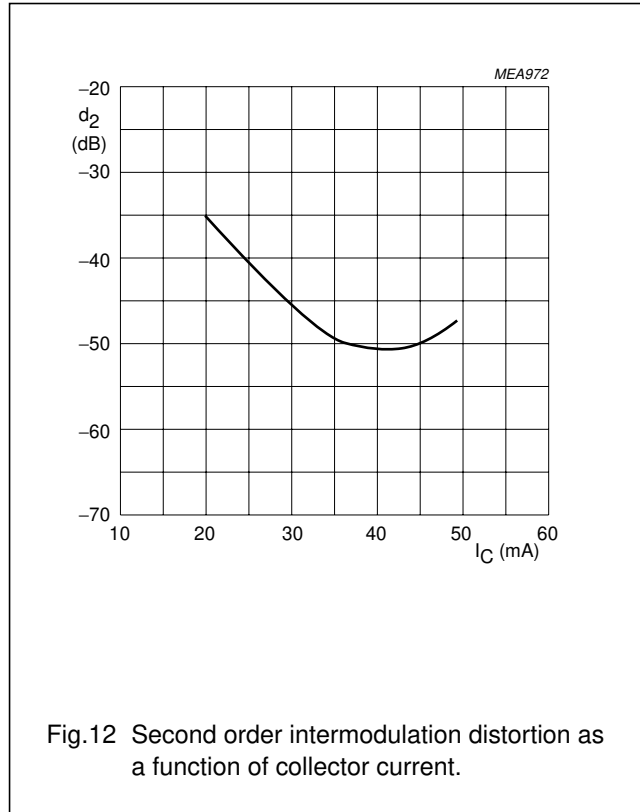
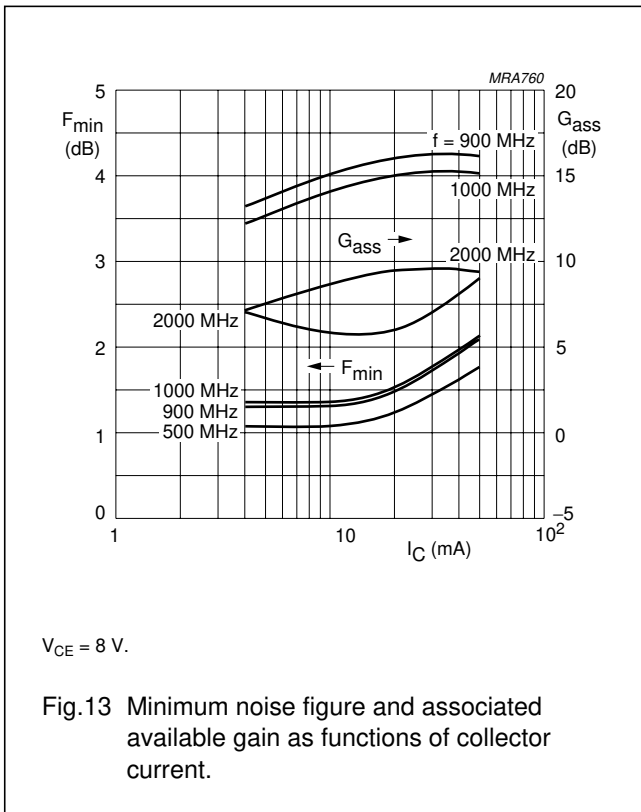
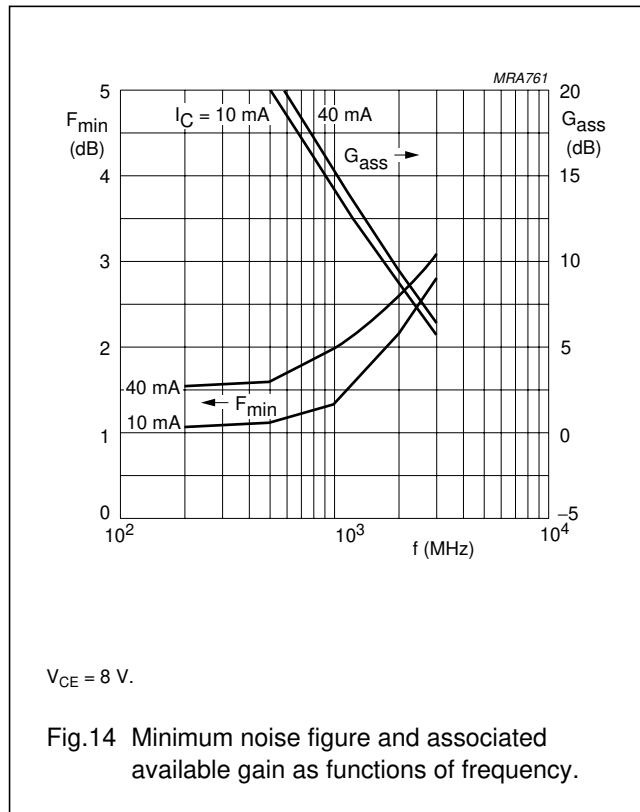


Fig.12 Second order intermodulation distortion as a function of collector current.



$V_{CE} = 8$ V.

Fig.13 Minimum noise figure and associated available gain as functions of collector current.

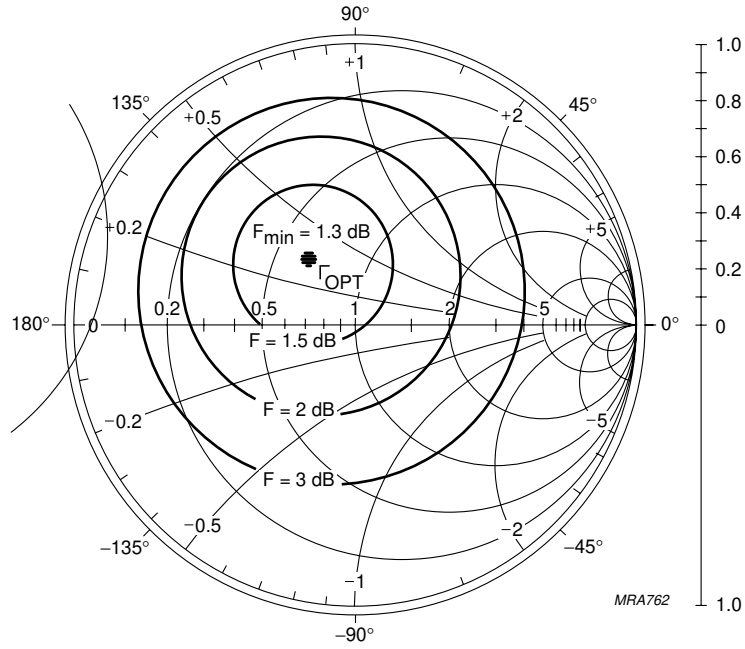


$V_{CE} = 8$ V.

Fig.14 Minimum noise figure and associated available gain as functions of frequency.

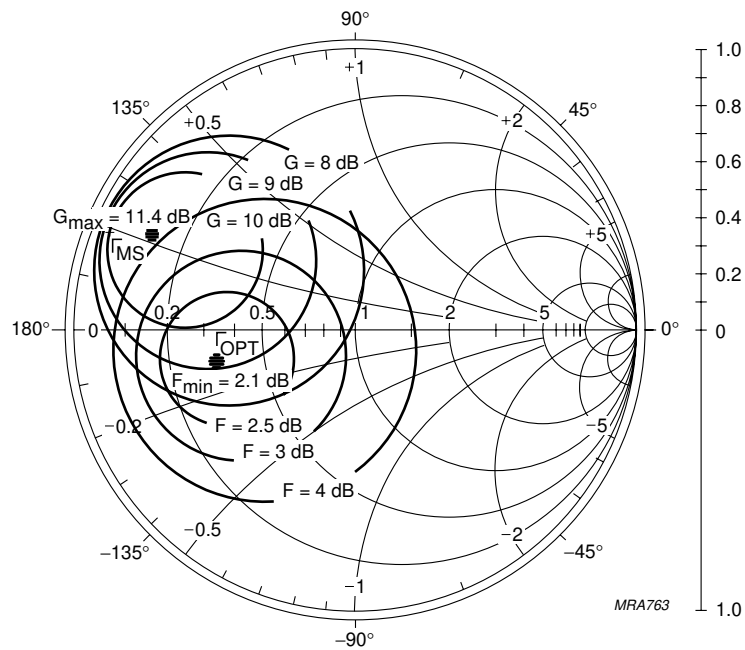
NPN 9 GHz wideband transistor

BFG540; BFG540/X;
BFG540/XR



$I_C = 10 \text{ mA}$; $V_{CE} = 8 \text{ V}$; $Z_0 = 50 \Omega$; $f = 900 \text{ MHz}$.

Fig.15 Noise circle figure.

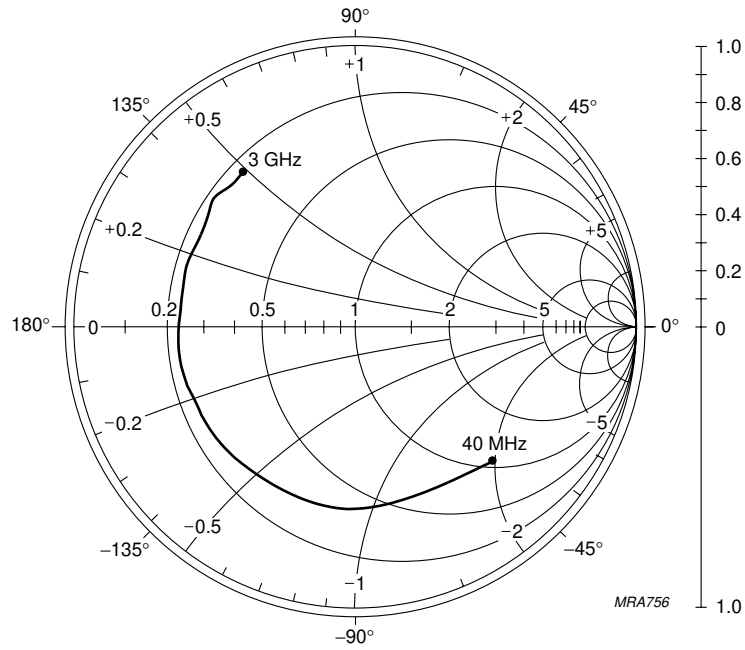


$I_C = 10 \text{ mA}$; $V_{CE} = 8 \text{ V}$; $Z_0 = 50 \Omega$; $f = 2 \text{ GHz}$.

Fig.16 Noise circle figure.

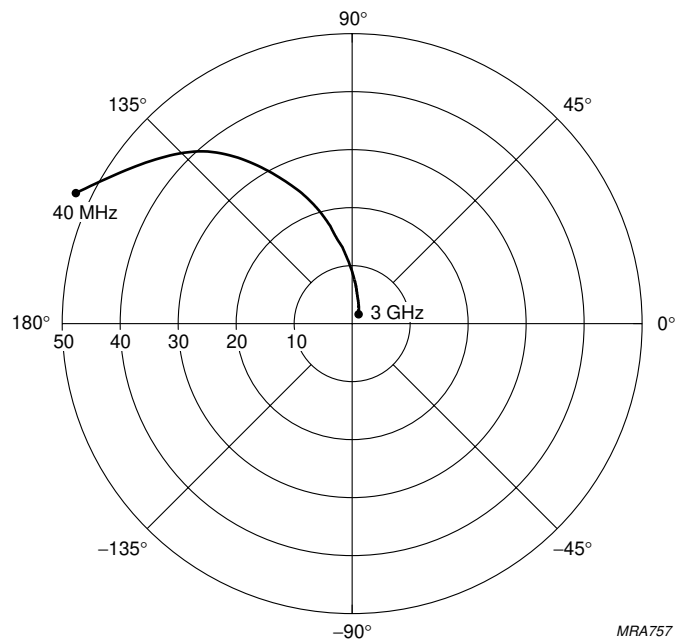
NPN 9 GHz wideband transistor

BFG540; BFG540/X;
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$I_C = 40 \text{ mA}$; $V_{CE} = 8 \text{ V}$; $Z_0 = 50 \Omega$.

Fig.17 Common emitter input reflection coefficient (s_{11}).

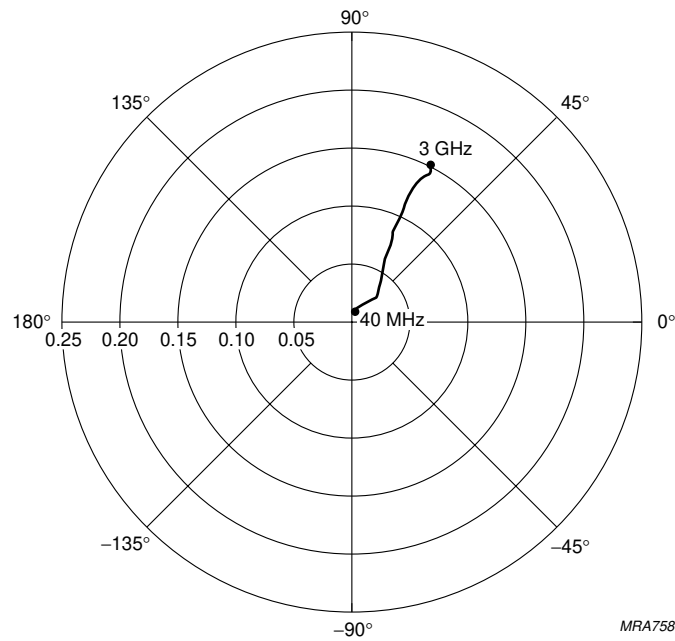


$I_C = 40 \text{ mA}$; $V_{CE} = 8 \text{ V}$.

Fig.18 Common emitter forward transmission coefficient (s_{21}).

NPN 9 GHz wideband transistor

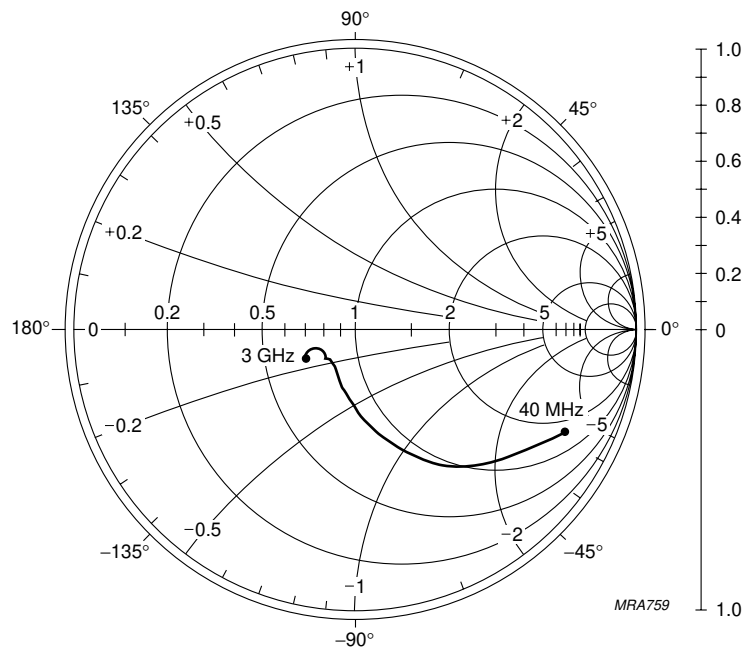
BFG540; BFG540/X;
BFG540/XR



$I_C = 40 \text{ mA}; V_{CE} = 8 \text{ V}.$

MRA758

Fig.19 Common emitter reverse transmission coefficient (s_{12}).



$I_C = 40 \text{ mA}; V_{CE} = 8 \text{ V}; Z_0 = 50 \Omega.$

MRA759

Fig.20 Common emitter output reflection coefficient (s_{22}).

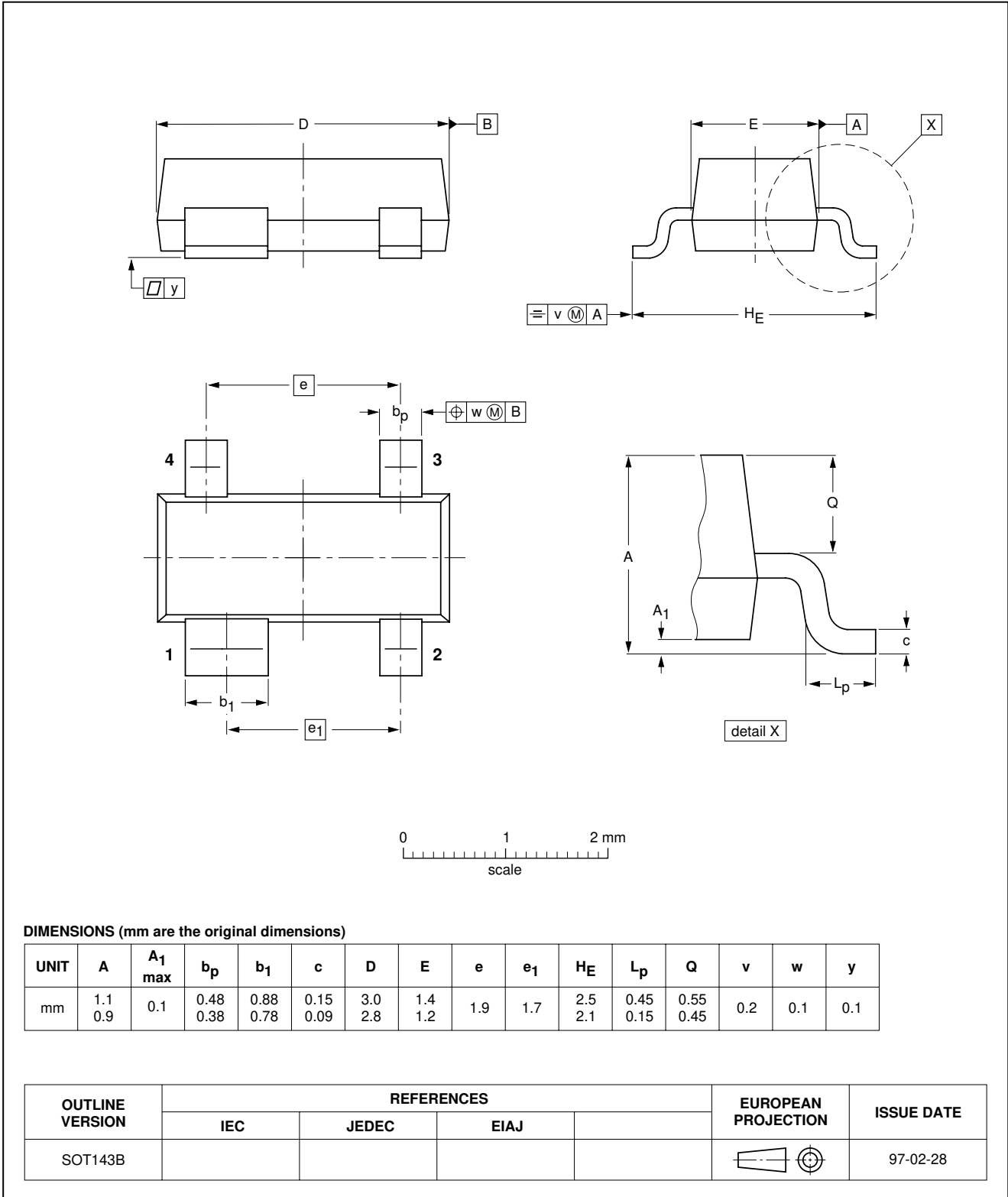
NPN 9 GHz wideband transistor

BFG540; BFG540/X;
BFG540/XR

PACKAGE OUTLINES

Plastic surface mounted package; 4 leads

SOT143B

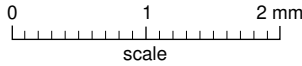
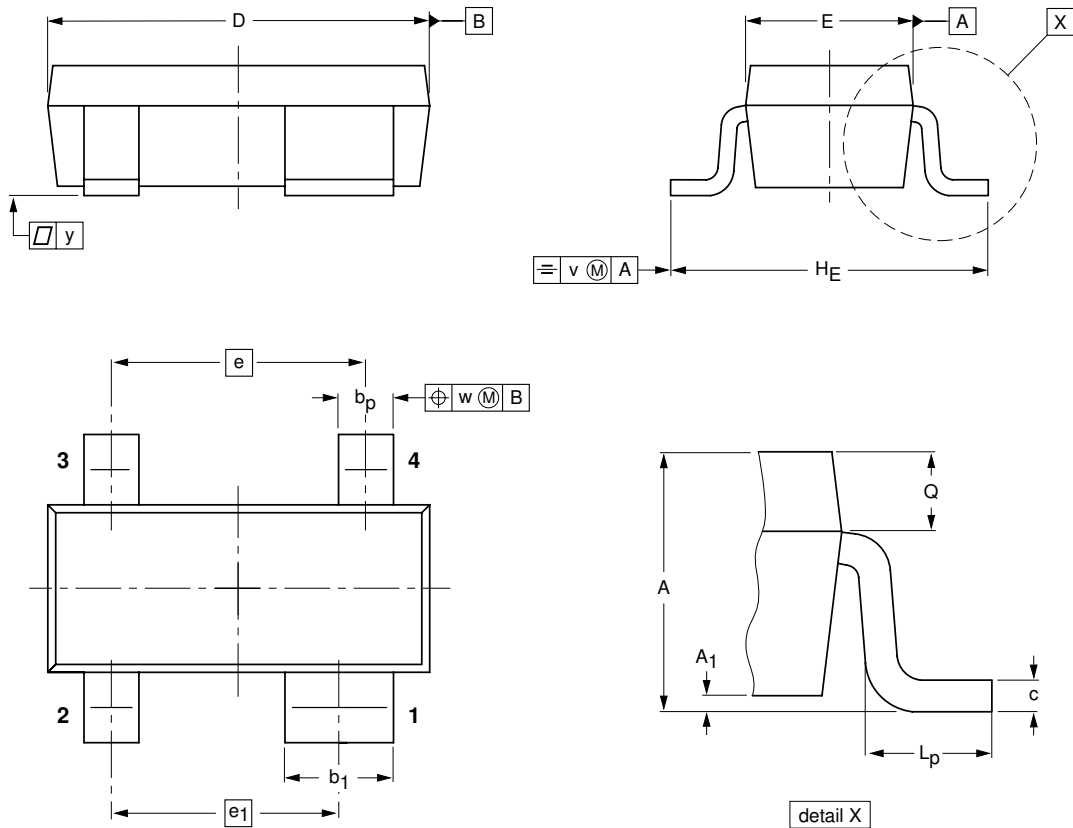


NPN 9 GHz wideband transistor

BFG540; BFG540/X;
BFG540/XR

Plastic surface mounted package; reverse pinning; 4 leads

SOT143R



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	b ₁	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.55 0.25	0.45 0.25	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT143R			SC-61B			97-03-10 99-09-13

Legal information

Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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Revision history

Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFG540_X_XR_N_5	20071121	Product data sheet	-	BFG540_X_XR_4
Modifications:	<ul style="list-style-type: none"> Pinning table on page 2; changed code 			
BFG540_X_XR_4 (9397 750 07059)	20000523	Product specification	-	BFG540XR_3
BFG540XR_3 (9397 750 03144)	19950901	Product specification	-	BFG540XR_2
BFG540XR_2	-	Product specification	-	BFG540XR_1
BFG540XR_1	-	-	-	-

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Date of release: 21 November 2007

Document identifier: BFG540_X_XR_N_5